

## 5 Pin Mini-Flat DMC-Isolator®

# 1 Mbit/s High Speed Transistor Coupler

#### **Features**

- High speed: 1 Mbit/s
- High isolation voltage between input and output (Viso=3750 Vrms)
- Guaranteed performance from 0°C to 70°C
- RoHS and REACH compliance
- Halogen Free compliance
- MSL class 1
- Regulatory Approvals
  - UL UL1577 (E364000)
  - VDE EN60747-5-5(VDE0884-5)
  - CQC GB4943.1, 2022 (14001105803)
  - IEC62368 (FI/41119)

#### **Description**

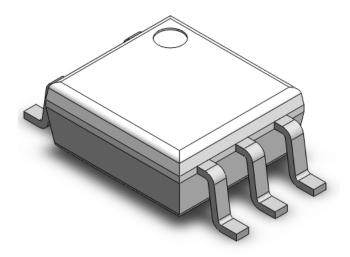
The CTM452 and CTM453 devices each consist of an infrared emitting diode, optically coupled to a high speed photo detector transistor.

A separate connection for the photodiode bias and Wide operating temperature range of -55°C to 125°C output-transistor collector increase the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor. The devices are packaged in a Mini-Flat package.

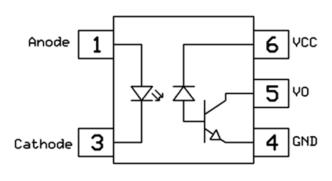
## **Applications**

- Line receivers
- Telecommunication equipment
- Feedback loop in switch-mode power supplies
- Home appliances
- High speed logic ground isolation

# **Package Outline**



### **Schematic**





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## Absolute Maximum Ratings $T_A = 25^{\circ}C$ , unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	3750	V <sub>RMS</sub>	
Topr	Operating temperature	-55 ~ +125	°C	
Тѕтс	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature (For 10 seconds)	260	°C	
Emitter			·	
l <sub>F</sub>	Forward current	25	mA	
I <sub>FP</sub>	Peak forward current (50% duty, 1ms P.W)	50	mA	
I <sub>F(TRANS)</sub>	Peak transient current (≤1µs P.W,300pps)	1	А	
V <sub>R</sub>	Reverse voltage	5	V	
P <sub>D</sub>	Power dissipation	45	mW	
Detector			·	
P <sub>D</sub>	Power dissipation	100	mW	
I <sub>O(AVG)</sub>	Average Output current	8	mA	
I <sub>O</sub> (Peak)	Peak Output current	16	mA	
Vo	Output voltage	-0.5 to 20	V	
Vcc	Supply voltage	-0.5 to 30	V	



# CTM452, CTM453 5 Pin Mini-Flat DMC-Isolator®

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#### **Electrical Characteristics** $T_A = 0.70$ °C (unless otherwise specified). Typical values are measured at $T_A = 25$ °C and $V_{cc} = 5V$

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	IF = 16mA	-	1.6	1.8	V	
VR	Reverse Voltage	IR = 10μA	5.0	-	-	V	
ΔV <sub>F</sub> /ΔT <sub>A</sub>	Temperature coefficient of forward voltage	IF =16mA	-	-1.6	-	mV/°C	

#### **Detector Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
	Logic High Output Current	I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =5.5V,		0.001	0.5		
		T <sub>A</sub> =25°C	-				
		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =3.3V,		0.001	0.4	μA	
Іон		T <sub>A</sub> =25°C					
		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =15V,	- 0.01	1			
		T <sub>A</sub> =25°C		0.01	'		
		I <sub>F</sub> =0mA, V <sub>O</sub> =V <sub>CC</sub> =15V	-	-	50		
ICCL	Logic Low Supply Current	I <sub>F</sub> =16mA, V <sub>O</sub> =Open,		- 120	- 120 200		
ICCL	Logic Low Supply Current	Vcc=15V	•		200	μA	
	$\begin{tabular}{ll} I_{F}=0mA,\ V_{O}=Open,\ V_{CC}=15V,\\ T_{A}=25^{\circ}C \\ \hline \\ IF=0mA,\ VO=Open,\\ \hline \end{tabular}$		0.01	1			
loou		T <sub>A</sub> =25°C	•	0.01	'	۸	
ICCH		IF=0mA, VO=Open,		-		μΑ	
		Vcc =15V	-		2		



# 5 Pin Mini-Flat DMC-Isolator®

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**Electrical Characteristics**  $T_A = 0 - 70^{\circ}\text{C}$  (unless otherwise specified). Typical values are measured at  $T_A = 25^{\circ}\text{C}$  and  $V_{\text{CC}} = 5V$ 

#### **Transfer Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
		I <sub>F</sub> =16mA, V <sub>O</sub> =0.4V,	20	-	50		
		Vcc=4.5V, T <sub>A</sub> =25°C					
		I <sub>F</sub> =16mA, V <sub>O</sub> =0.5V,	15	-	-	- %	
CTD		Vcc=4.5V					
CTR	Current Transfer Ratio	I <sub>F</sub> =16mA, V <sub>O</sub> =0.4V,	40		54		
		Vcc=3.3V, T <sub>A</sub> =25°C	18		51		
		I <sub>F</sub> =16mA, V <sub>O</sub> =0.5V,	13				
		Vcc=3.3V					
		I <sub>F</sub> =16mA, I <sub>O</sub> =3mA, V <sub>CC</sub> =4.5V,			0.4	- v	
		T <sub>A</sub> =25°C	-	-	0.4		
		I <sub>F</sub> =16mA, I <sub>O</sub> =3mA, V <sub>CC</sub> =3.3V,			0.4		
W	Logic Low Output Voltage	T <sub>A</sub> =25°C			0.4		
VoL		I <sub>F</sub> =16mA, I <sub>O</sub> =2.4mA,	-	-	0.5	V	
		Vcc=4.5V					
		I <sub>F</sub> =16mA, I <sub>O</sub> =2.4mA,			0.5		
		V <sub>CC</sub> =3.3V					



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#### **Switching Characteristics**

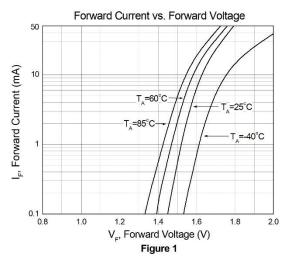
Symbol	Parameters		Test Conditions	Min	Тур	Мах	Units	Notes
	Propagation Delay Time Logic High to Logic Low		$I_F=16mA$ , $R_L=1.9K\Omega$ ,	-	0.35	0.8	μs	
			T <sub>A</sub> =25°C					
			$I_F$ =16mA, $R_L$ =1.9K $\Omega$	-	ı	1.0		
$T_PHL$			I <sub>F</sub> =16mA, V <sub>CC</sub> =3.3V		0.4	1		
			R <sub>L</sub> =1.9KΩ, T <sub>A</sub> =25°C					
			I <sub>F</sub> =16mA, V <sub>CC</sub> =3.3V		1	1 1		
			R <sub>L</sub> =1.9KΩ			1.4		
	Propagation Delay Time Logic Low to Logic High		$I_F=16mA, R_L=1.9K\Omega,$		0.3	0.8		
			T <sub>A</sub> =25°C	_			- - µs	
			I <sub>F</sub> =16mA, R <sub>L</sub> =1.9KΩ	-	-	1.0		
$T_PLH$			I <sub>F</sub> =16mA, V <sub>CC</sub> =3.3V			1.5		
			R <sub>L</sub> =1.9KΩ, T <sub>A</sub> =25°C			1.5		
			I <sub>F</sub> =16mA, V <sub>CC</sub> =3.3V		2.0	2.0		
			R <sub>L</sub> =1.9KΩ			2.0		
	Common Mode	CTM452	I <sub>F</sub> = 0mA , V <sub>CM</sub> =10Vp-p,	5,000	_	-		
СМн	Transient Immunity at	C1101452	R <sub>L</sub> =1.9KΩ, T <sub>A</sub> =25°C	3,000	_		V/µs	
CIVIH	Logic High	•	I <sub>F</sub> = 0mA , V <sub>CM</sub> =1500Vp-p,	15,000	_		ν/μδ	
	Logic Flight	OTWHOO	R <sub>L</sub> =1.9KΩ, T <sub>A</sub> =25°C	10,000				
CML	Common Mode  Transient Immunity at  Logic Low	CTM452 t CTM453	$I_F = 16\text{mA}$ , $V_{CM}=10\text{Vp-p}$ ,	5,000	_	-		
			R <sub>L</sub> =1.9KΩ, T <sub>A</sub> =25°C				V/µs	
OIVIL			I <sub>F</sub> = 16mA , V <sub>CM</sub> =1500Vp-p,	15,000	-		ν/μ3	
	209.0 2011	31W-33	R <sub>L</sub> =1.9KΩ, T <sub>A</sub> =25°C					

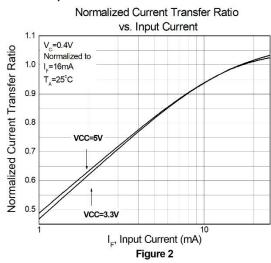


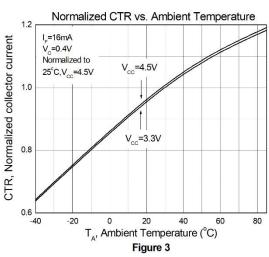
### 5 Pin Mini-Flat DMC-Isolator®

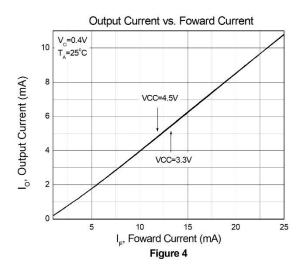
# 1 Mbit/s High Speed Transistor Coupler

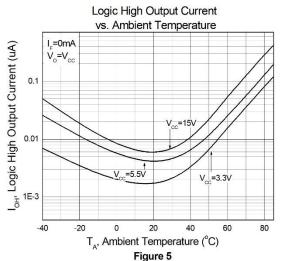
## Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

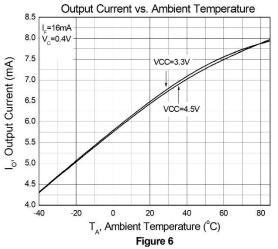










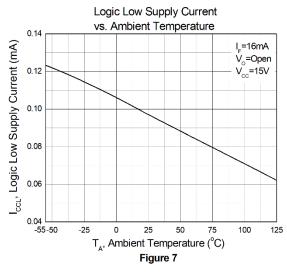


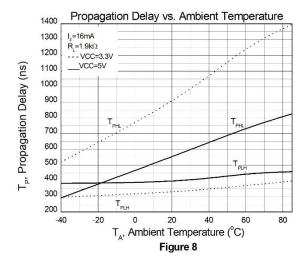


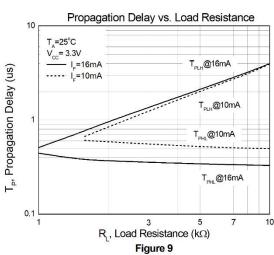
## 5 Pin Mini-Flat DMC-Isolator®

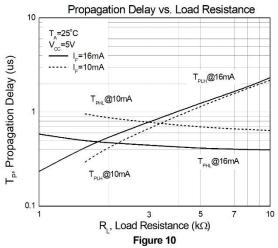
# 1 Mbit/s High Speed Transistor Coupler

## Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified





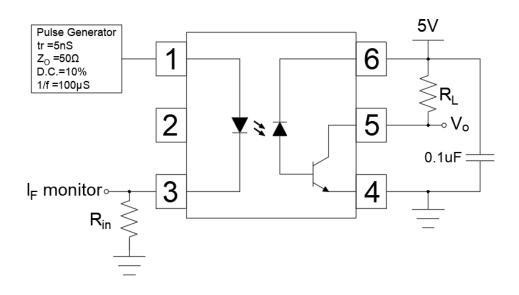


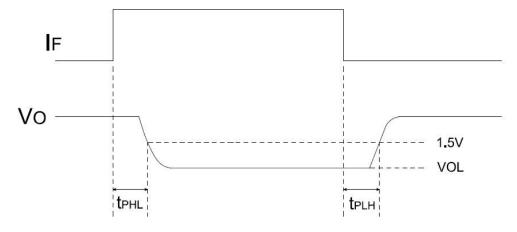




# 1 Mbit/s High Speed Transistor Coupler

#### **Test Circuits**



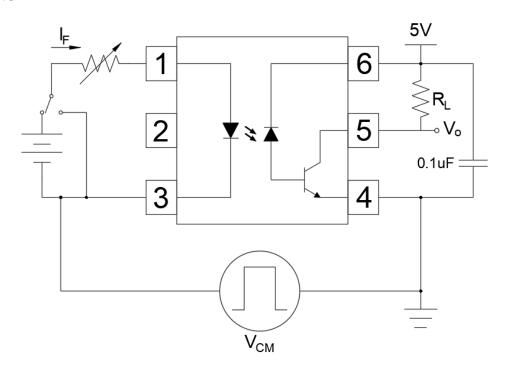


**Figure 11: Switching Time Test Circuits** 



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#### **Test Circuits**



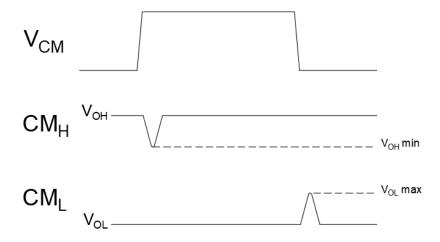
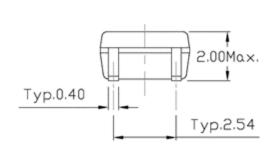


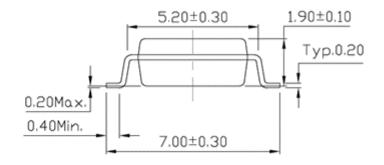
Figure 12: CMR Test Circuits

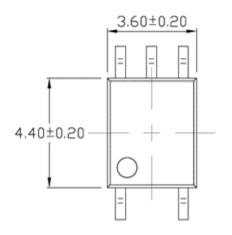


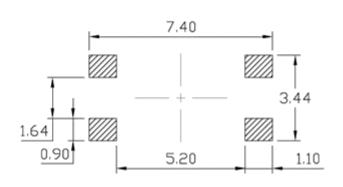


#### Package Dimension Dimensions in mm unless otherwise stated

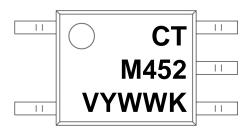








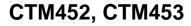
# **Marking Information**



#### Note:

CT: Denotes "CT Micro" M452: Product Number

V : VDE Safety Mark OptionY : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code





# 1 Mbit/s High Speed Transistor Coupler

## **Ordering Information**

CTM45X (V)(Z)

CT = Denotes "CT Micro"

M45X = Product Number (X= 2, or 3)

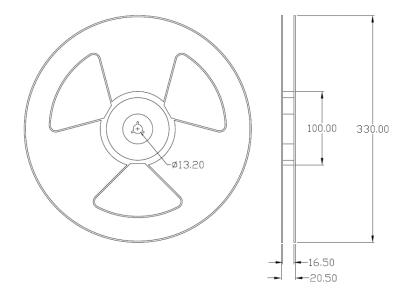
V = VDE Safety Mark Option (Blank or V)

Z = Tape and Reel Option (T1 or T2)

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Tapping	3000 Units/Reel
T2	T2 Surface Mount Lead Forming – With Option 2 Tapping	

#### Reel Dimension All dimensions are in mm, unless otherwise stated

#### Option T1/T2





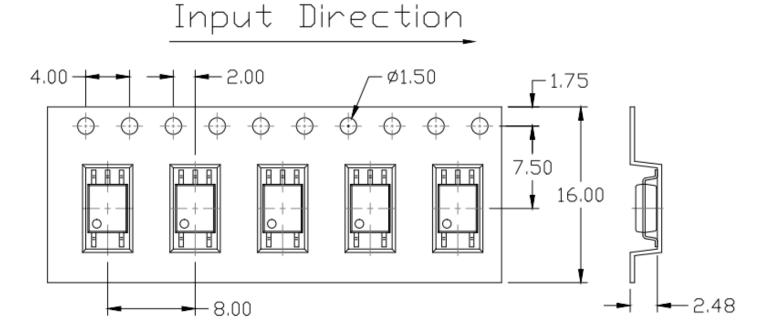
#### Carrier Tape Specifications Dimensions in mm unless otherwise stated

-8.00

## **Option T1**

# 

#### **Option T2**



2.48



# 1 Mbit/s High Speed Transistor Coupler

#### Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

#### **Wave soldering (Follow the JEDEC standard JESD22-A111)**

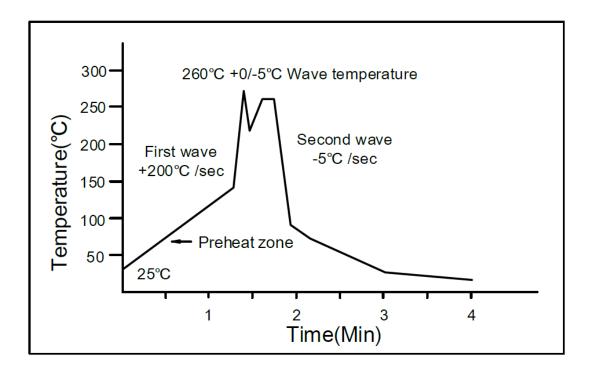
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



# Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

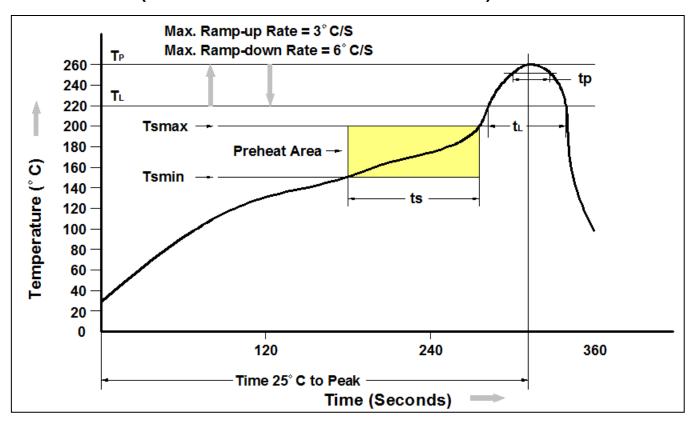
One time soldering is recommended. Temperature: 350±10°C

Time: 5 sec max.



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## Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.